

PATENT ASSIGNMENT

Electronic Version v1.1
Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"><thead><tr><th>Name</th><th>Execution Date</th></tr></thead><tbody><tr><td>LI JIANG</td><td>12/04/2011</td></tr><tr><td>MINGQI LI</td><td>12/04/2011</td></tr></tbody></table>		Name	Execution Date	LI JIANG	12/04/2011	MINGQI LI	12/04/2011				
Name	Execution Date										
LI JIANG	12/04/2011										
MINGQI LI	12/04/2011										
RECEIVING PARTY DATA											
<table border="1"><tr><td>Name:</td><td>SEMICONDUCTOR MANUFACTURING INTERNATIONAL (BEIJING) CORPORATION</td></tr><tr><td>Street Address:</td><td>18 WEN CHANG ROAD, ECONOMIC-TECHNOLOGICAL DEVELOPMENT AREA, DAXING DISTRICT</td></tr><tr><td>City:</td><td>BEIJING</td></tr><tr><td>State/Country:</td><td>CHINA</td></tr><tr><td>Postal Code:</td><td>100176</td></tr></table>		Name:	SEMICONDUCTOR MANUFACTURING INTERNATIONAL (BEIJING) CORPORATION	Street Address:	18 WEN CHANG ROAD, ECONOMIC-TECHNOLOGICAL DEVELOPMENT AREA, DAXING DISTRICT	City:	BEIJING	State/Country:	CHINA	Postal Code:	100176
Name:	SEMICONDUCTOR MANUFACTURING INTERNATIONAL (BEIJING) CORPORATION										
Street Address:	18 WEN CHANG ROAD, ECONOMIC-TECHNOLOGICAL DEVELOPMENT AREA, DAXING DISTRICT										
City:	BEIJING										
State/Country:	CHINA										
Postal Code:	100176										
PROPERTY NUMBERS Total: 1											
<table border="1"><thead><tr><th>Property Type</th><th>Number</th></tr></thead><tbody><tr><td>Application Number:</td><td>13323489</td></tr></tbody></table>		Property Type	Number	Application Number:	13323489						
Property Type	Number										
Application Number:	13323489										
CORRESPONDENCE DATA											
Fax Number: (805)373-0051											
Phone: 805-373-0060											
Email: jjirkovsky@koppelpatent.com											
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i>											
Correspondent Name: KOPPEL, PATRICK, HEYBL & PHILPOTT											
Address Line 1: 2815 Townsgate Road											
Address Line 2: SUITE 215											
Address Line 4: Westlake Village, CALIFORNIA 91361-5827											
ATTORNEY DOCKET NUMBER:	803-2F-029										
NAME OF SUBMITTER:	Michael J. Ram										
Total Attachments: 2 source=DOC_20111212160654_000#page1.tif source=DOC_20111212160654_000#page2.tif											

CH \$40.00 13323489

501752792

PATENT
REEL: 027367 FRAME: 0487

Docket No. 803-2F-029
IEE110147-US
2011-00267-SH-US

ASSIGNMENT

We, **Li Jiang**, citizen of Beijing, China, having an address of 18 Wen Chang Rd., Economic-Technological Development Area, Daxing District, Beijing 100176, P.R. China, and **Mingqi Li**, citizen of Beijing, China, having an address of 18 Wen Chang Rd., Economic-Technological Development Area, Daxing District, Beijing 100176, P.R. China, (hereinafter "Inventors"), represent that we have invented improvements in a new and useful "METHOD OF MANUFACTURING A SEMICONDUCTOR DEVICE" (hereinafter the "Invention") set forth in China Patent Application No. 201110235045.3, for which we have executed an application for Letters Patent of the United States of America on the same day as our execution of this Assignment.

SEMICONDUCTOR MANUFACTURING INTERNATIONAL (BEIJING) CORPORATION, is a Beijing corporation, has a place of business at 18 Wen Chang Rd., Economic-Technological Development Area, Daxing District, Beijing 100176, P.R. China, and desires to acquire the entire right, title and interest in and to the invention, application and Letters Patent to be granted and issued thereon.

For valuable consideration, the receipt and legal sufficiency of all of which we acknowledge, we have sold and do hereby sell, assign, transfer and set over unto SEMICONDUCTOR MANUFACTURING INTERNATIONAL (BEIJING) CORPORATION, its successors and assigns, the entire right, title and interest in and to the invention and all improvements thereon, in and to the application for Letters Patents thereon, in and to applications pertaining to or based upon the invention and application, including divisional and continuing applications and continuations-in-part, and in and to any and all Letters Patent which may be granted and issued on the invention and applications, or any of them, in the United States of America, its territories and possessions, and in all countries foreign thereto, together with and including all priority rights based upon any and all applications in the United States of America covered by this Assignment.

We also agree that we will, at the request of SEMICONDUCTOR MANUFACTURING INTERNATIONAL (BEIJING) CORPORATION, execute any and all applications for Letters Patent for the invention, execute any and all other papers and documents and do all other and further lawful acts that SEMICONDUCTOR MANUFACTURING INTERNATIONAL (BEIJING) CORPORATION may deem necessary or desirable to obtain Letters Patent on the invention, to secure the grant of such Letters Patent and to protect and vest in SEMICONDUCTOR MANUFACTURING INTERNATIONAL (BEIJING) CORPORATION the undivided interests in the right, title and interest in the invention, applications and Letters Patent.

Docket No. 803-2F-029
 IEE110147-US
 2011-00267-SH-US

We also authorize and empower SEMICONDUCTOR MANUFACTURING INTERNATIONAL (BEIJING) CORPORATION, its successors and assigns to apply for and obtain, in its or their own names, Letters Patent for the invention before competent International Authorities and in any and all countries foreign to the United States in which applications for Letters Patent can be so made or letters patent so obtained.

Dated 2011.12.04

WITNESS [Signature]
 (Type or print name below line)

[Signature]
 LI JIANG

WITNESS [Signature]
 (Type or print name below line)

Dated 2011.12.4

WITNESS [Signature]
 (Type or print name below line)

[Signature]
 MINGQI LI

WITNESS [Signature]
 (Type or print name below line)